



Principal Engineer - Package Concept Engineering

Job description

Do you want to design outstanding packages for innovative semiconductor technologies? Do you want to build the bridge between product requirements and package solutions? Do you want to shape package development from concept to implementation? If this sound like a perfect challenge to you, join us as Principal Engineer for Package Concept Engineering and you will work on best-in class package solutions that enable future package technologies and multi-chip modules. We are looking for you to bring in your technical expertise, to translate input from Infineon product experts and to develop the right package solution including latest packaging trends – exploring technical limits and possibilities.

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With this position you will be entering our „technical ladder”: our career path for experts. You will be able to focus deeply on technology – while further pursuing your career. As you continually expand your expert knowledge, puzzle over matters and solve problems, you will position yourself as a thought leader – thus helping our products improve our world a bit more each day.

In your new role you will:

- Define the **package strategies and roadmaps (performance, design and cost aspects)** with focus on **latest packaging trends** especially in the area of **SiP, Chiplets, wafer level, and BGA**
- Use your expert knowledge as well as **simulation tools and design tools** to **assess technical requirements** and to find fast solutions
- **Collaborate** closely with product/ technology development, application engineering and marketing to **work out the best solutions for Wireless and Computing applications**
- **Support** our customers with **package specific questions**
- Observe and proactively **act on trends** in package development through **continuous market screening and competitor analysis**
- **Identify business opportunities** enabled by new technologies and concepts

At a glance

Location: **(Singapore)**
Job ID: **351042**
Start date: **as soon as possible**
Entry level: **5+ years**
Type: **Full time**
Contract: **Permanent**

Apply to this position online by following the URL and entering the Job ID in our job search:

Job ID: **351042**
www.infineon.com/jobs



Profile

You have a clear idea of how innovation contributes to business success. To achieve your ambitious goals, you cooperate across borders, recognize the contribution of others and use the resulting creative potential. Furthermore, you remain solution-oriented, open and flexible even when under pressure.

Beyond, you are best-equipped for this role if you have:

- A technical background through a degree in Electronics, Physics, Material Sciences, Microsystems Technology or similar
- At least 10 years' practical experience in **assembly technologies, ideally in package concept/ design or package development** in the semiconductor industry and within multi-cultural teams
- Good experience with **typical package design tools (e.g. AutoCAD)**
- Good understanding of Wireless and Computing applications
- Very good communication and presentation skills
- A high motivation to expand your scope
- Fluent in English
- Occasional willingness to travel

Why Us

Part of your life. Part of tomorrow.

Infineon is a world leader in semiconductor solutions that make life easier, safer, and greener. Our solutions for efficient energy management, smart mobility, and secure, seamless communications link the real and the digital world.

In accordance with the requirements set by the Singaporean Government, Infineon Technologies Asia Pacific Pte Ltd ("Infineon") can only allow individuals who are (a) fully vaccinated, (b) certified to be medically ineligible for a vaccine or (c) have recovered from COVID-19 within a prescribed period, onto company premises. Therefore, Infineon requires all new employees, as well as contractors and business partners, to be fully vaccinated against COVID-19. "Fully vaccinated" means individuals have completed the full regime of an approved COVID-19 Vaccine as listed under the World Health Organization (WHO) Emergency Use Listing (EUL) including the respective post-vaccination period to ensure the vaccine has become full effective. Anyone who is unable to be vaccinated due to an approved and/or recognised exemption condition may apply for special consideration.

